

CORROSION RESISTANT MEMBER FOR MANUFACTURING SEMICONDUCTOR

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Abstract of JP11102900

PROBLEM TO BE SOLVED: To improve the manufacturing yield of semiconductors and to allow high-quality semiconductor elements to be manufactured by using a material mainly consisting of boron carbide as a material for forming members including the inner wall members of semiconductor manufacturing equipment, particularly plasma processing equipment, and tools such as support members for supporting an object to be processed.

SOLUTION: In a semiconductor manufacturing equipment such as plasma processing equipment for manufacturing semiconductor elements such as high-density circuit elements, members including inner wall members and tools such as support members for supporting an object to be processed, which are exposed to a halogen-containing corrosive gas such as CF₄, SF₆ or BC_l3, or plasma thereof, are formed of a boron carbide (B₄C) sintered body whose relative density is 90% or higher, or desirably, whose strength is 300 MPa or higher.

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